

Title (en)

LENS DRIVING DEVICE, AND CAMERA MODULE AND OPTICAL DEVICE COMPRISING SAME

Title (de)

LINSENANSTEUERUNGSVORRICHTUNG UND KAMERAMODUL SOWIE OPTISCHE VORRICHTUNG DAMIT

Title (fr)

DISPOSITIF DE DÉPLACEMENT DE LENTILLE, MODULE DE CAMÉRA ET DISPOSITIF OPTIQUE LES COMPRENANT

Publication

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Application

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- KR 20160129981 A 20161007
- EP 17858656 A 20170926
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Abstract (en)

An embodiment of the present invention comprises: a housing; a bobbin disposed inside the housing; a first coil disposed on an outer circumferential surface of the bobbin; a magnet disposed on a side part of the housing to correspond to the first coil; a base disposed under the housing; a second coil, disposed on a lateral surface of the base, for generating an induced voltage by interacting with the first coil; and first to fourth elastic members coupled to the bobbin and the housing, and spaced apart from an upper surface of the base, wherein each of the first and second elastic members comprises: a first bonding part for bonding the first coil, and a first connection terminal for electrical connection to the outside; each of the third and fourth elastic members comprises: a second bonding part for bonding the second coil, and a second connection terminal for an electrical connection to the outside; and the second bonding part and the second connection terminal are disposed on different outer surfaces of the base.

IPC 8 full level

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Citation (search report)

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DOCDB simple family (application)

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